

F

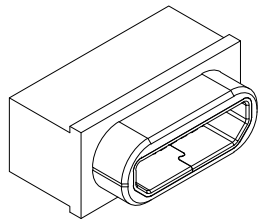
E

D

C

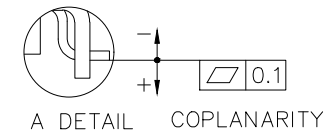
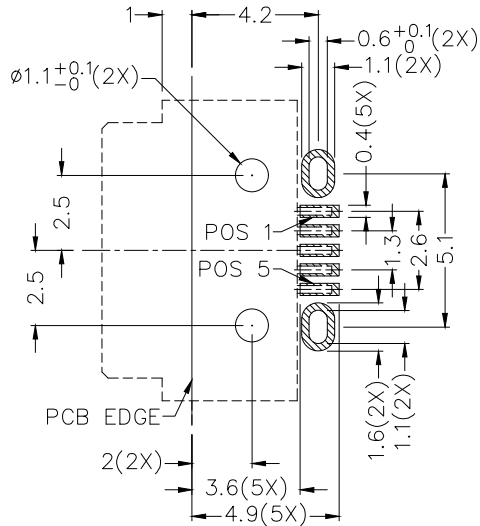
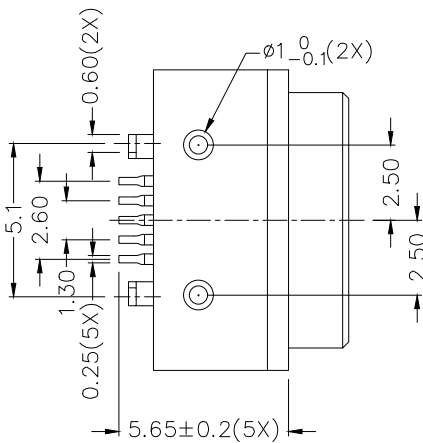
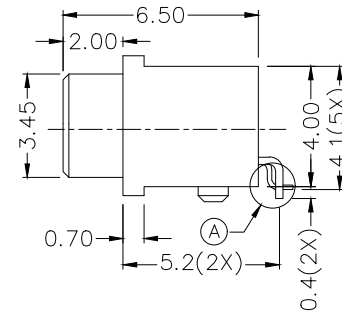
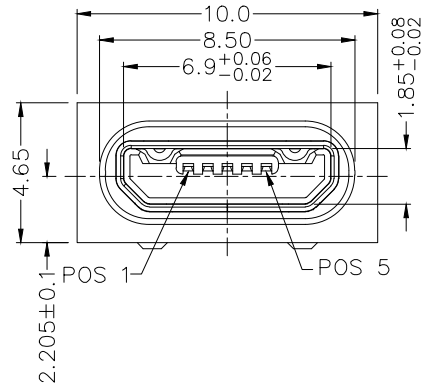
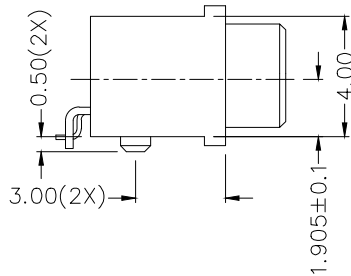
B

A



RoHS
Compliant

ZONE	SYMBOL	REVISION	APPROVAL	DATE
		ADD ASSEMBLY O-RING DIAGRAM	H.Q.ZHOU	27-1-2024




RECOMMENDED PCB LAYOUT
TOLERANCE: ±0.05
(TOP VIEW)

DESCRIPTION	MATERIAL	PLATING
TERMINALS	COPPER ALLOY	NICKEL PLATED ON ALL AREA, GOLD FLASH ON CONTACT & SOLDER AREA
SHELL	STAINLESS STEEL	NICKEL PLATED
HOUSING	HIGH TEMP. PLASTIC	
INSULATOR	HIGH TEMP. PLASTIC	

 LINKPLEX TECHNOLOGY LIMITED

DESIGN	H.L.TAN	DATE	23-7-2015	SCALE	4:1
DRAWING	J.H.ZHOU	DATE	27-1-2024	MATERIAL	
CHECK	T.Y.LI	DATE	27-1-2024	DWG. NO.	TZ\WP4002D-H3-A/3.0
APPROVAL	H.Q.ZHOU	DATE	27-1-2024	SHEET	1/2

PART NAME	WATERPROOF USB MICRO B	TOLERANCE UNLESS	0.0±0.2	UNIT:	
PART NO.	LWP-4002D-H3	OTHERWISE SPECIFIED:	0.00±0.1 0.000±0.05	mm	

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B

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D

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B

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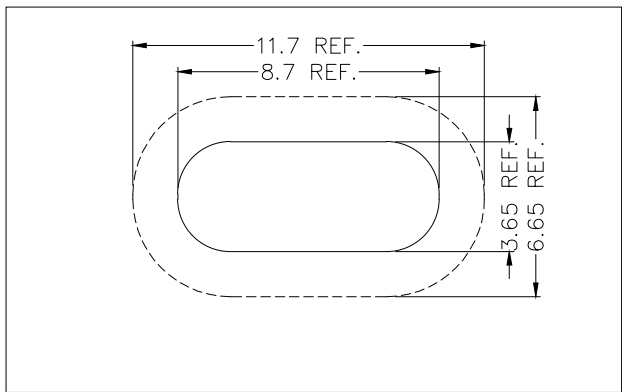


RoHS Compliant

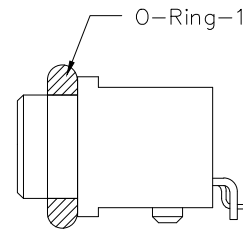
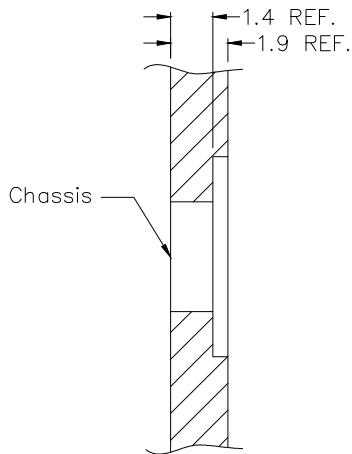
ZONE	SYMBOL	REVISION	APPROVAL	DATE

1

1

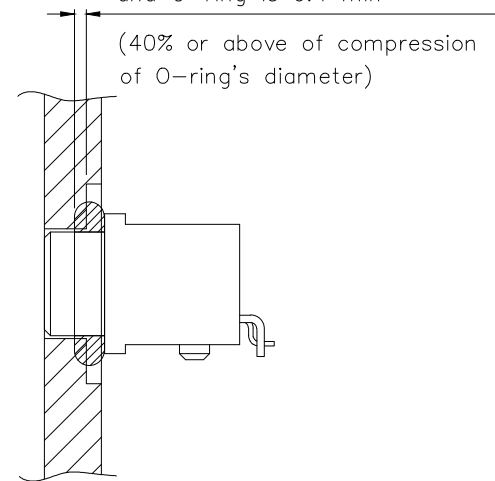


Top View



Interference gap between chassis and O-ring is 0.4 min

(40% or above of compression of O-ring's diameter)



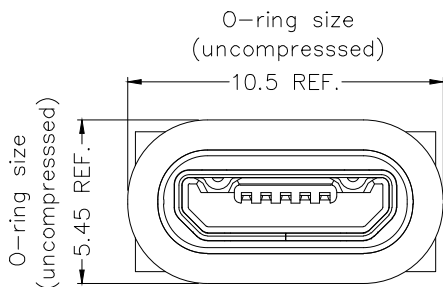
After assembling on chassis

2

2

3

3



4

4



LINKPLEX TECHNOLOGY LIMITED

DESIGN	H.L.TAN	DATE	23-7-2015	SCALE	4:1
DRAWING	J.H.ZHOU	DATE	27-1-2024	MATERIAL	
CHECK	T.Y.LI	DATE	27-1-2024	DWG. NO.	TZ\WP4002D-H3-A/3.0
APPROVAL	H.Q.ZHOU	DATE	27-1-2024	SHEET	2/2

PART NAME	WATERPROOF USB MICRO B	TOLERANCE UNLESS	0.0±0.2	UNIT:	mm
PART NO.	LWP-4002D-H3	OTHERWISE SPECIFIED:	0.00±0.1 0.000±0.05		

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